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Sheet 1 of 1

FORM PTO-1449	Atty. Docket No. 169 12-0528	Application No. 10 055,688
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANT'S INFORMATION DISCLOSURE STATEMENT	First Named Inventor: Zine-Eddine Boutaghoul	Group Art. 2812
	Filing Date: January 23, 2002	

U.S. PATENT DOCUMENTS

Examiner Initial	Document No.	Date	Name	Class	Sub Class	Filing Date If Appropriate
AA						
AB						
AC						
AD						
AE						
AF						
AG						
AH						
AI						
AJ						
AK						

FOREIGN PATENT DOCUMENTS

	Document No.	Date	Country	Class	Sub Class	Translation Yes No
AL						
AM						
AN						

OTHER ART (Including Author, Title, Date, Pertinent Pages, Etc.)

AO	Singh, Angad et al., Batch Transfer of Microstructures Using Flip-Chip Solder Bump Bonding
AP	Maharbiz, Michael et al., Batch Micropackaging by Compression-Bonded Wafer-Wafer Transfer
AQ	

EXAMINER: <i>[Signature]</i>	DATE CONSIDERED: <i>11-7-02</i>
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EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.